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DEWEY
10-18-01PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application No.: 09/821,695
Filing Date: March 29, 2001
Applicant: Mikio SAITO
Group Art Unit: N/A
Examiner: Not Yet Assigned
Title: METHOD AND APPARATUS FOR EXAMINING
THROUGH HOLES
Attorney Docket: 9319S-000195

Hon. Commissioner of Patents and Trademarks
Washington, D.C. 20231

PRELIMINARY AMENDMENT

Sir:

Prior to the examination of this application, please amend it as follows:

IN THE SPECIFICATION

A1 [0002] Conventionally, examinations of through holes each having a diameter of several ten ~ several hundred micron millimeters are generally conducted to check if a correct number of the through holes are opened, if the sizes of the through holes are uniform, if any foreign matters are present in the through holes, and the like. Optical methods are generally conducted for such examinations. For example, an area sensor camera is used to photograph an examining surface of a work piece where through holes are formed, and an image processing apparatus is used to compare the